



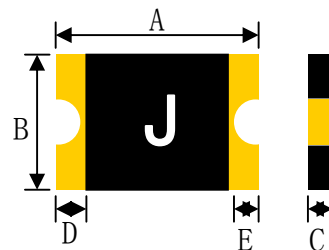
# Shenzhen Wondhope Electric Co.,Ltd.

Add:2/F, Bldg 3, Minxing Industrial Zone, Minkang Rd, Minzhi Office, Longhua New Area, Shenzhen	package:	SMD 1206
	Model:	WH110
	V <sub>max</sub> :	6V
	I <sub>max</sub> :	40A
Tel: 86-0755-29503668-8047	SS:	ROHS
Fax :86-0755-29503998	Web:	<a href="http://www.wondhope.com">www.wondhope.com</a>
Email:sunny@wondhope.com      P.C.:518131		

## Specification Sheet

### Marking :

J: Part identification



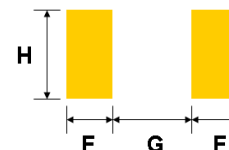
Appearance and size of production

### Solderability:

Meets EIA specification RS186-9Eand  
ANSI/J-STD-002 Category 3

### Terminal Pad Materials:

Sn-plated nickle-copper, lead-free device.



Recommended pad layout

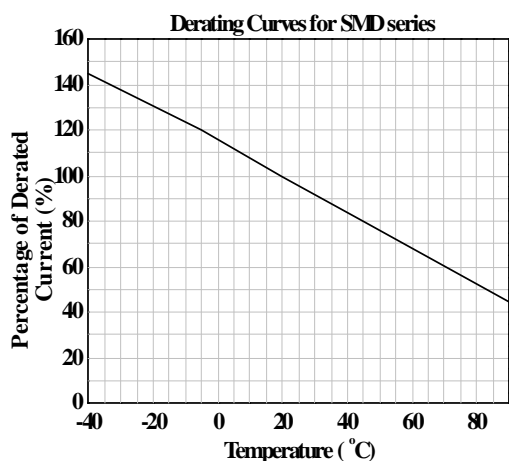
### Dimensions:

	A		B		C		D	E	F	G	H
UNIT	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MIN			
mm	3	3.5	1.5	1.8	0.5	1.2	0.15	0.1	1	2	1.9
inch	0.12	0.14	0.06	0.07	0.020	0.050	0.006	0.004	0.04	0.08	0.07

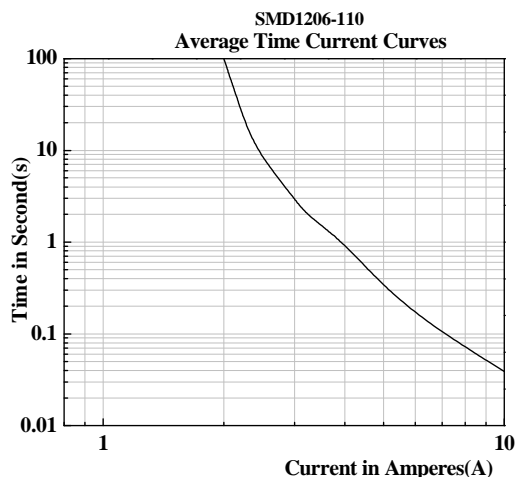
### Performance Specification:

Model	V <sub>max</sub> (V <sub>dc</sub> )	I <sub>max</sub> (A)	I <sub>hold</sub> @25°C (A)	I <sub>trip</sub> @25°C (A)	P <sub>d</sub> Tpy. (W)	Maximum Time To Trip		Resistance	
						Current (A)	Time (Sec)	Ri <sub>min</sub> (Ω)	R1 <sub>max</sub> (Ω)
SMD110	6	40	1.10	2.20	0.8	8.0	0.30	0.055	0.220
V <sub>max</sub> : Maximum voltage , device can withstand without damage at rated current;									
I <sub>max</sub> : Maximum fault current, device can withstand without damage at rated voltage;									
I <sub>hold</sub> : Hold Current.,device will sustain for 30min without tripping in 25°C still air;									
I <sub>trip</sub> : Minimum current at which the device will trip in 25°C still air;									
P <sub>d</sub> : Power dissipated from device when in the tripped state in 25°C still air;									
Ri <sub>min</sub> :Minimum resistance of device in initial (un-soldered) state;									
R1 <sub>max</sub> : Maximum resistance of device at 25°C measured one hour post reflow.									

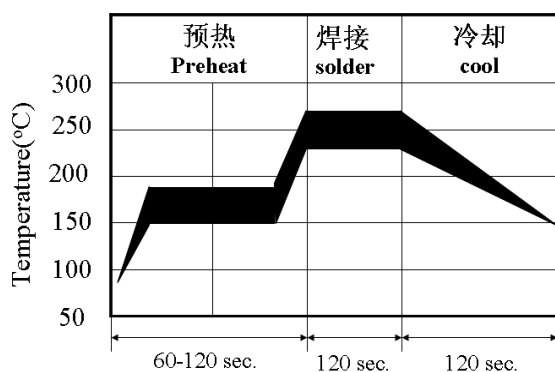
## Average Time Current Curve



## Average Time Current Curve at 25°C



## Solder reflow conditions



- 1、 Recommended reflow methods: IR, vapor phase oven, hot air oven.
- 2、 Devices are not designed to be wave soldered to the bottom side of the board.
- 3、 Recommended maximum paste thickness is 0.25 mm (0.010 inch).
- 4、 Devices can be cleaned using standard method and solvents.

**Note:** If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

## Storage and Handling

Storage conditions: 30°C max, 60% R.H. Devices may not meet specified performance if storage conditions are exceeded.

## Order Information

J=Part identification, SMD1206=Packaging, 110=Model  
3500pcs/Reel

## WARNING:

- 1、 Use PPTC exceed by the maximum rating and improper use may result in device damage and possible electrical arcing and flame.
- 2、 PPTC are designed for protection against over current or temperature fault conditions and should not be used when repeated fault conditions or prolonged trip events are anticipated.
- 3、 Device performance can be impacted negatively if devices are handled in a manner inconsistent with recommended electronic, thermal, and mechanical procedures for electronic components.
- 4、 Use PPTC with a large inductance in circuit will generate a circuit voltage above the rated voltage of the PPTC.
- 5、 Avoid impact PPTC device its thermal expansion like placed under pressure or installed in limited space.
- 6、 If any quality problems caused by improper use mentioned above, our company is not responsible.